


RELIABILITY REPORT  
FOR  
MAX4614CUD+  
PLASTIC ENCAPSULATED DEVICES

June 28, 2010

**MAXIM INTEGRATED PRODUCTS**

120 SAN GABRIEL DR.  
SUNNYVALE, CA 94086

<b>Approved by</b>

Quality Assurance
T. J. [unclear], Reliability Engineering

## Conclusion

The MAX4614CUD+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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### I. Device Description

#### A. General

The MAX4614/MAX4615/MAX4616 quad, low-voltage, high-speed, single-pole/single-throw (SPST) analog switches are pin compatible with the industry-standard 74HC4066/MAX4610 analog switches. On-resistance ( $10 \text{ } \Omega$  max) is matched between switches to  $1 \text{ } \Omega$  max and is flat ( $1 \text{ } \Omega$  max) over the specified signal range. Each switch handles V+ to GND analog signal levels. Maximum off-leakage current is only 1nA at TA = +25°C and 6nA at TA = +85°C. The MAX4614 has four normally open (NO) switches, and the MAX4615 has four normally closed (NC) switches. The MAX4616 has two NO switches and two NC switches. These CMOS switches operate from a single +2V to +5.5V supply. All digital inputs have +0.8V and +2.4V logic thresholds, ensuring TTL/CMOS-logic compatibility when using a single +5V supply.

**II. Manufacturing Information**

A. Description/Function:	Low-Voltage, High-Speed, Quad, SPST CMOS Analog Switches
B. Process:	TS60
C. Number of Device Transistors:	
D. Fabrication Location:	Taiwan
E. Assembly Location:	Malaysia, Philippines, Thailand
F. Date of Initial Production:	July 24, 1999

**III. Packaging Information**

A. Package Type:	14-pin TSSOP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-1201-0135
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Ja:	110°C/W
K. Single Layer Theta Jc:	30°C/W
L. Multi Layer Theta Ja:	100.4°C/W
M. Multi Layer Theta Jc:	30°C/W

**IV. Die Information**

A. Dimensions:	62 X 55 mils
B. Passivation:	Si <sub>3</sub> N <sub>4</sub> /SiO <sub>2</sub> (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal 1 - 0.9 microns / Metal 2 - 0.9 microns (as drawn)
F. Minimum Metal Spacing:	Metal 1 - 0.9 microns / Metal 2 - 0.9 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO <sub>2</sub>
I. Die Separation Method:	Wafer Saw

## V. Quality Assurance Information

- A. Quality Assurance Contacts: Ö[ ] • (T æ æ ^!, Reliability Engineering)  
Bryan Preeshl (Managing Director of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.  
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

## VI. Reliability Evaluation

### A. Accelerated Life Test

The results of the 135 biased (static) life test are shown in Table 1. Using these results, the Failure Rate ( $\lambda$ ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{6.21}{192 \times 4340 \times 160 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 23.3 \times 10^{-9}$$

$\lambda = 23.3$  F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maxim-ic.com/qa/reliability/monitor>. Cumulative monitor data for the TS60 Process results in a FIT Rate of 0.5 @ 25C and 8.57 @ 55C (0.8 eV, 60% UCL)

### B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

### C. E.S.D. and Latch-Up Testing

The AH23 die type has been found to have all pins able to withstand a HBM transient pulse of +/-1000V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of +/-250mA.

**Table 1**  
Reliability Evaluation Test Results

**MAX4614CUD+**

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
<b>Static Life Test</b> (Note 1)				
	Ta = 135 Biased Time = 192 hrs.	DC Parameters & functionality	160	2
<b>Moisture Testing</b> (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
<b>Mechanical Stress</b> (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data